ISOLA LAMINATE SYSTEMS

FR406BC

High Performance Epoxy Laminate for Buried Capacitance

FR406BC is a high performance FR-4 laminate system engineered to meet the high reliability demands of high density, embedded capacitance applications. FR406BC provides the processing ease of an FR-4 material while offering outstanding dimensional consistency and thickness tolerance. The performance attributes of FR406BC makes it ideal for high density, high layer count and critical impedance applications.

Performance and Processing Advantages

• High Tg - 160°C (DSC)

Superior performance through multiple thermal excursions Superior chemical and thermal resistance Lower CTE from ambient to 288°C

- **Tight Thickness Tolerance** Superior thickness tolerance capability for consistent controlled impedance
- Consistent Dimensional Stability
 Repeatable and reliable movement for critical high layer count application

Purchasing Information

- Industry Approvals
 IPC4101/24
 UL Recognized FR-4, File Number E41625
 (Part of Isola's FR-4 Family)
 CSA
- Availability

Thicknesses: 0.002" Available in sheet or panel form **Copper Foil Cladding:** Double Treat HTE Glass Styles - 6060

Product and Solutions Offering

Isola Laminate Systems' broad range of laminate, prepreg and foil products and solutions includes:

• PWB Substrates FR-4s Composites

Advanced PWB

- Substrates
- BT/Epoxy Polyimide Specialty Prepregs
- HDI Materials
- Signal Integrity Substrates

isola

- Buried Passive Solutions FR406BC
- Packaging Substrates

Ordering Information

FR406BC Typical Laminate Properties, 0.002"

Contact your local sales representative or the Inside Sales Department in La Crosse, WI.

Phone: 1-800-845-2904 or 608-784-6070 Fax: 1-800-344-1825 or 608-791-2428

Isola Laminate Systems Corp. 230 North Front Street La Crosse, WI 54601

For further information visit *www.isolalaminatesystems.com*

PROPERTY	<u>UNITS</u>	IPC 4101	FR406BC VALUE	CONDITIONING
Thickness	inches	<.030	0.002	_
	mm	[<.78]	_	_
Construction		_	I-6060	_
Retained Resin	—	—	58%	_
Thermal				
Tg, min (DSC)	°C	150-200	160	E-2/105
CTE - x-axis	ppm/°C		14	Ambient to Tg
y-axis	ppm/°C		13	Ambient to Tg
z-axis	ppm/°C		140	Ambient to 288°C
Solder Float, 288°C	seconds		120	Condition A
<u>Electrical</u>				
Permittivity (DK), max. @				
I MHz (2 Fluid Cell)		5.4	4.4	C-24/23/50
500 MHz (HP 4291)			4.20	C-24/23/50
I GHz (HP4291)			4.21	C-24/23/50
Loss Tangent (DF), max. @				
I MHz (2 Fluid Cell)		0.035	0.023	C-24/23/50
500 MHz (HP 4291)			0.014	C-24/23/50
I GHz (HP4291)			0.014	C-24/23/50
Surface Resistivity, min.	megohms	lx10⁴	3×10 ⁶	C-96/35/90
	megohms	1×10 ³	8x10 ⁶	E-24/125
Volume Resistivity, min.	megohm-cm	lx10⁰	9×10⁰	C-96/35/90
	megohm-cm	1×10 ³	2×10 ⁶	E-24/125
Electric Strength, min.	volts/mil	736	1000	D-48/50
0	[volts/mm]	[2.9x10⁴]	[3.9x10⁴]	_
Arc Resistance, min.	seconds	60	90	D-48/50
Comparative Tracking Index	volts		220	ASTM D-36/38-85
(UL)	PLC-UL	3	3	UL94
Physical				
Peel Strength, min 1 oz.	lb/in		7.5	Condition A
J.	[Kg/M]		[125]	Condition A
	lb/in	4.5	6.0	After Thermal Stress
	[Kg/M]	[80]	[105]	After Thermal Stress
	lb/in	3.9	6.0	E-1/125
	[Kg/M]	[70]	[105]	E-1/125
Flammability		V-0	V-0	UL94

"The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold."